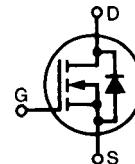


# MegaMOS™FET

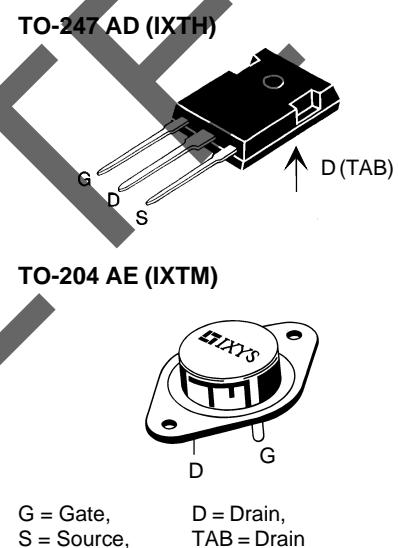
**IXTH 50N20**  
**IXTM 50N20**

**V<sub>DSS</sub> = 200 V**  
**I<sub>D25</sub> = 50 A**  
**R<sub>DS(on)</sub> = 45 mΩ**

## N-Channel Enhancement Mode



Symbol	Test Conditions	Maximum Ratings		
V <sub>DSS</sub>	T <sub>J</sub> = 25°C to 150°C	200	V	
V <sub>DGR</sub>	T <sub>J</sub> = 25°C to 150°C; R <sub>GS</sub> = 1 MΩ	200	V	
V <sub>GS</sub>	Continuous	±20	V	
V <sub>GSM</sub>	Transient	±30	V	
I <sub>D25</sub>	T <sub>C</sub> = 25°C	50	A	
I <sub>DM</sub>	T <sub>C</sub> = 25°C, pulse width limited by T <sub>JM</sub>	200	A	
P <sub>D</sub>	T <sub>C</sub> = 25°C	300	W	
T <sub>J</sub>		-55 ... +150	°C	
T <sub>JM</sub>		150	°C	
T <sub>stg</sub>		-55 ... +150	°C	
M <sub>d</sub>	Mounting torque	1.13/10	Nm/lb.in.	
<b>Weight</b>		TO-204 = 18 g, TO-247 = 6 g		
		300	°C	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s				



Symbol	Test Conditions	Characteristic Values			
		(T <sub>J</sub> = 25°C, unless otherwise specified)	min.	typ.	max.
V <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	200			V
V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2		4	V
I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V <sub>DC</sub> , V <sub>DS</sub> = 0			±100	nA
I <sub>DSS</sub>	V <sub>DS</sub> = 0.8 • V <sub>DSS</sub> V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C	200	1	μA mA
R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 I <sub>D25</sub> Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %		0.045		Ω

## Features

- International standard packages
- Low R<sub>DS(on)</sub> HDMOS™ process
- Rugged polysilicon gate cell structure
- Low package inductance (< 5 nH)
  - easy to drive and to protect
- Fast switching times

## Applications

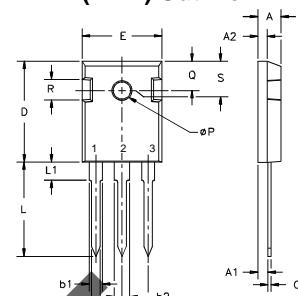
- Switch-mode and resonant-mode power supplies
- Motor controls
- Uninterruptible Power Supplies (UPS)
- DC choppers

## Advantages

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values		
		( $T_j = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.
$g_{fs}$	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$ , pulse test	20	32	S
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	4600	pF	
		800	pF	
		285	pF	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 2 \Omega$ , (External)	18	25	ns
		15	20	ns
		72	90	ns
		16	25	ns
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$	190	220	nC
		35	50	nC
		95	110	nC
$R_{thJC}$			0.42	K/W
$R_{thCK}$			0.25	K/W

## TO-247 AD (IXTH) Outline



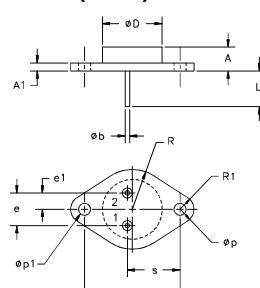
Terminals: 1 - Gate  
2 - Drain  
3 - Source Tab - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	.205	.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	.232	.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

## Source-Drain Diode

Symbol	Test Conditions	Characteristic Values		
		( $T_j = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.
$I_s$	$V_{GS} = 0 \text{ V}$	50N20	50	A
$I_{SM}$	Repetitive; pulse width limited by $T_{JM}$		200	A
$V_{SD}$	$I_F = I_s, V_{GS} = 0 \text{ V},$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2 \%$		1.5	V
$t_{rr}$	$I_F = I_s, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 100 \text{ V}$	400		ns

## TO-204AE (IXTM) Outline



Pins 1 - Gate 2 - Source  
Case - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	6.4	11.4	.250	.450
A <sub>1</sub>	1.53	3.42	.060	.135
Øb	1.45	1.60	.057	.063
ØD		22.22		.875
e	10.67	11.17	.420	.440
e <sub>1</sub>	5.21	5.71	.205	.225
L	11.18	12.19	.440	.480
Øp	3.84	4.19	.151	.165
Øp <sub>1</sub>	3.84	4.19	.151	.165
q	30.15	BSC	1.187	BSC
R	12.58	13.33	.495	.525
R <sub>1</sub>	3.33	4.77	.131	.188
s	16.64	17.14	.655	.675

Fig. 1 Output Characteristics

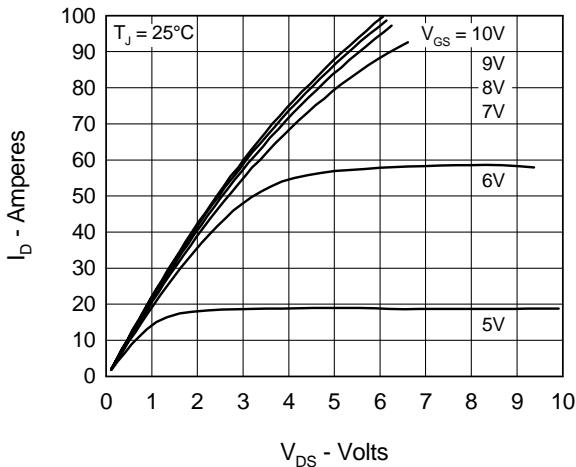
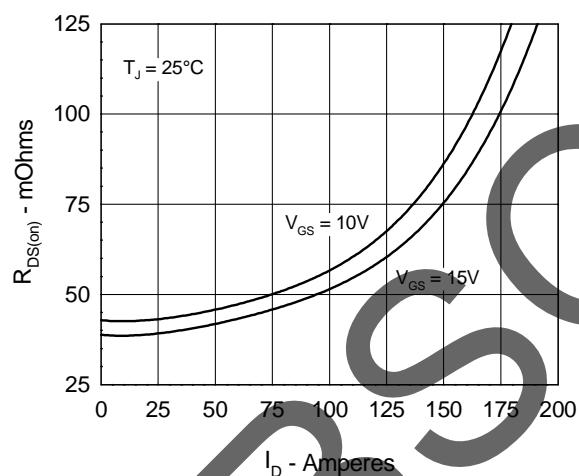
Fig. 3  $R_{DS(on)}$  vs. Drain Current

Fig. 5 Drain Current vs. Case Temperature

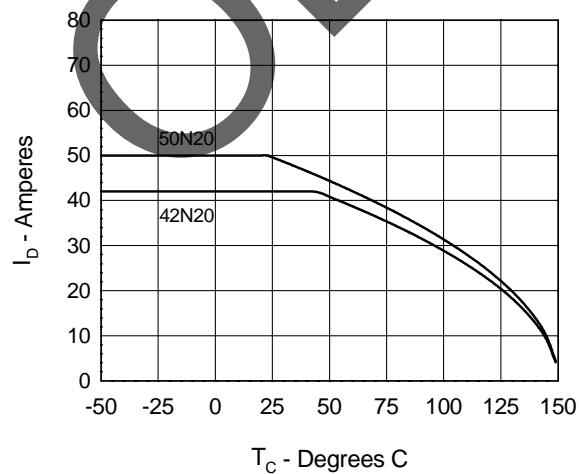


Fig. 2 Input Admittance

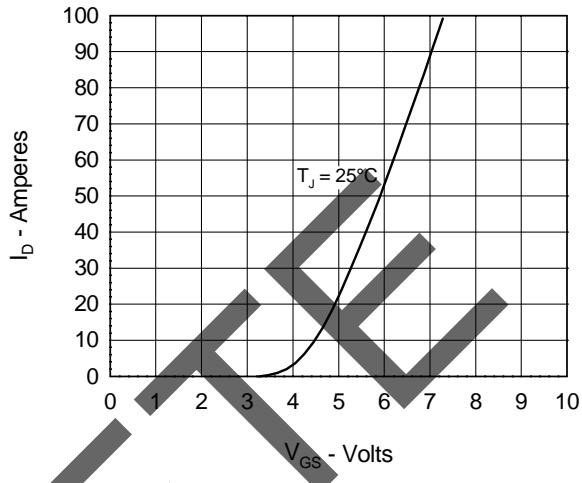


Fig. 4 Temperature Dependence of Drain to Source Resistance

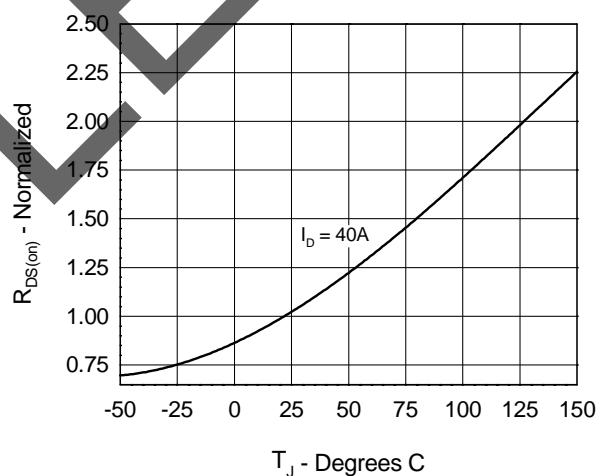


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

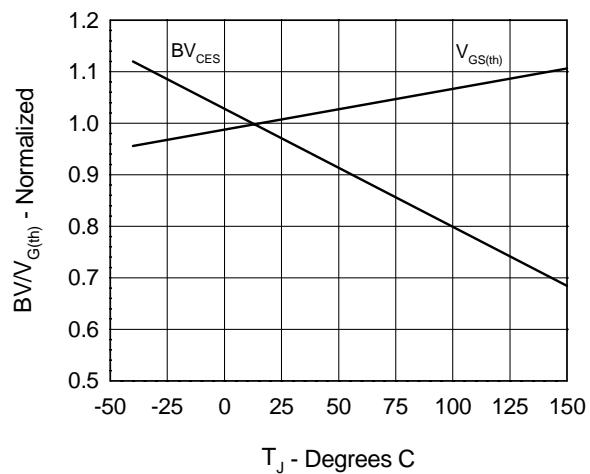


Fig.7 Gate Charge Characteristic Curve

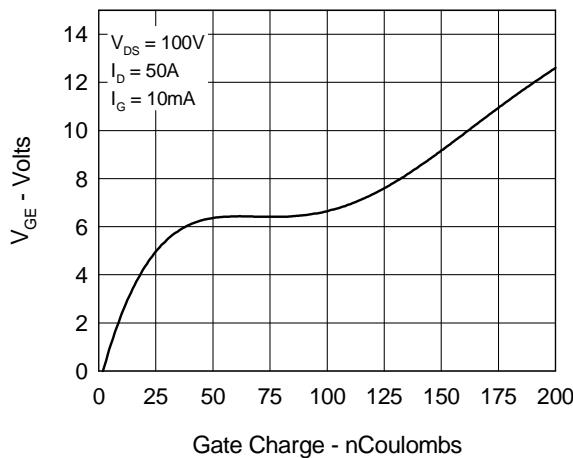


Fig.9 Capacitance Curves

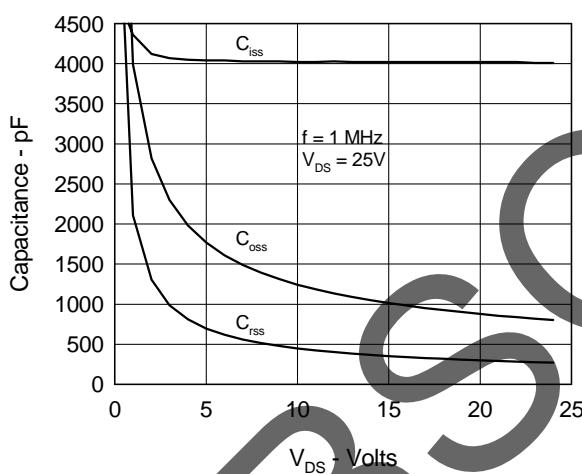


Fig.11 Transient Thermal Impedance

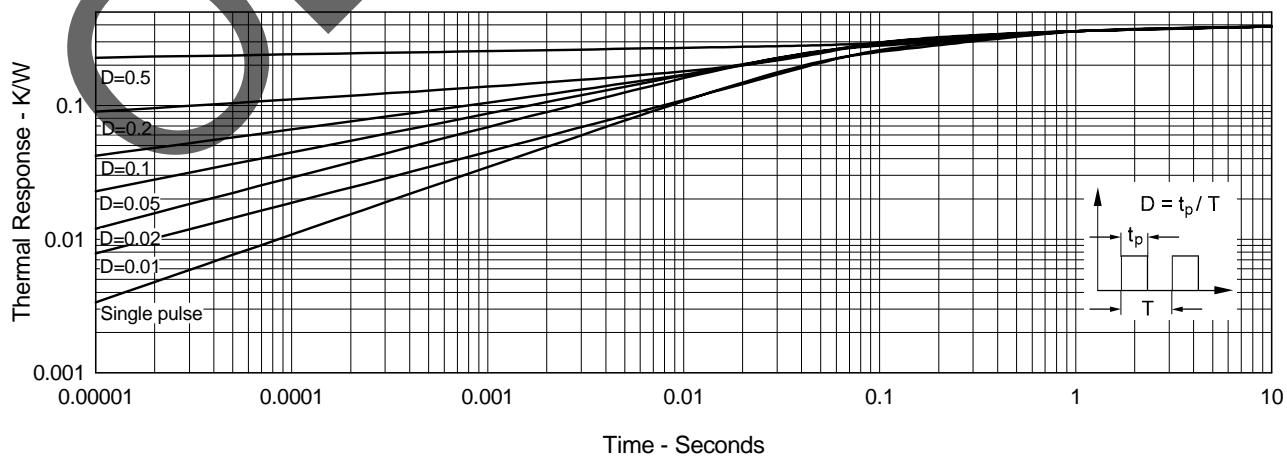


Fig.8 Forward Bias Safe Operating Area

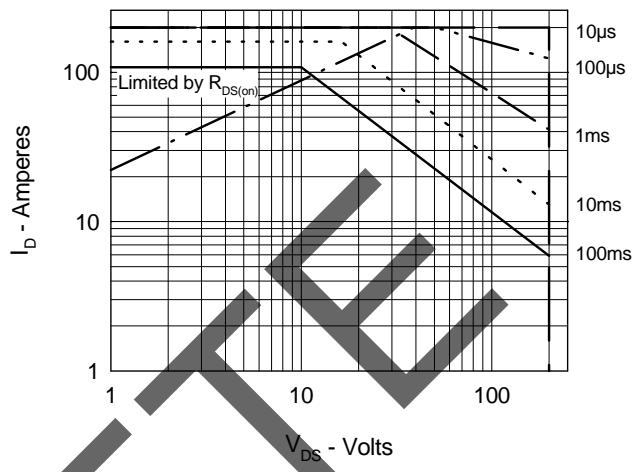


Fig.10 Source Current vs. Source to Drain Voltage

